Nordson YESTECH's advanced megapixel color camera imaging technology offers high-speed PCB inspection with exceptional defect coverage. With one top-down viewing camera, four side viewing cameras and 3D inspection, the FX-940 inspects solder joints and verifies correct part assembly enabling users to improve quality and increase throughput.

Programming the FX-940 is fast and intuitive. Operators typically take less than 30 minutes to create a complete inspection program including solder inspection. The FX-940 utilizes a standard package library to simplify training and ensure program portability across manufacturing lines.

Advanced Fusion Lighting and newly available image processing technology integrates several techniques, including 3D inspection, color inspection, normalized correlation and rule-based algorithms, to provide complete inspection coverage with an unmatched low false failure rate.

Configurable for all line positions, the FX-940 is equally effective for paste, pre / post-reflow and final assembly inspection. Off-line programming maximizes machine utilization and real-time SPC monitoring provides a valuable yield enhancement solution.

Features:
• Proprietary megapixel color imaging
• Capture on-the-fly technology
• 1 top-down and 4 side angle cameras
• Quick set-up
• High speed
• High defect coverage / low false failure
• Optional 3D inspection

Automated Inspection for:
• Solder defects
• Lead defects / lifted leads
• Component presence and position
• Correct part / polarity
• Through-hole parts
• Co-planarity of chips, BGAs and other height sensitive devices
Specifications

Model
FX-940

Optional Upgrades:
4 side angle cameras
Digital Fringe Projection 3D Inspection

Specifications

Multi-function system with top-down viewing,
Capture on the fly technology

Optional Upgrades:
Up to 30 sq. in./sec. > 1.5 million components per hour
2” (50mm) top and bottom
0.020; 0.0105 with high magnification option
<500 PPM (<0.05% typical);
Port: position, missing, wrong, polarity,
skew, tombstone
Lead: bent, lifted, bridging
Solder: open, insufficient, short, solder balls

Software

Algorithms:
Color, OCV, OCR, barcode recognition, both image and
rule-based algorithms. Optional 3D

Data Requirements:
ASCII Text, X-Y position, part #, ref. #, polarity

CAD Translation Package:
Argis, Unicam, Fabmaster, YESTECH CAD Utility

Programming Skill Level:
Technician or operator

Operating System:
Windows 7

Offline Software:
Optional - Rework, Review and Program Creation

Data Outputs:
Text, SQL, ODBC, MS Access

Hardware

Material Handling:
SMEMA, dual direction auto width conveyor,
pass / fail signals, board clamping

Lighting:
Proprietary Fusion Lighting™ multiangle LED
Up to 18 megapixel color camera sensor
25, 12 or 8 micron pixel size

Imager:

Options

Conveyor:
Dual lane conveyor, heavy duty chain conveyor and 3 stage
Optional 48” x 21” (1219mm x 510mm)

Large Board Option
Optional for bottom side bar codes

Bottom Side Camera:
Optional for bottom side bar codes

Board Supports:
Bottom side

Facilities

Power:
110-220VAC, 50/60 Hz, 15 amps

Air input:
60 PSI max., 1/4” air hose, 2 CFM

Footprint:
20” x 21” (500mm x 525mm)

Weight:
950 lbs (430 kg)

Machine Installation:
< 1 hour

Nordson YESTECH
USA Headquarters:
2762 Loker Ave. West
Carlsbad, CA USA 92010
+1.760.918.8471 Phone
+1.760.918.8472 Fax

China:
#137 Guoshoujing Road
Zhangjiang Hi-Tech Park
Pudong,
Shanghai 201203, PR.China
+86.21.3866.9166 Phone
+86.21.3866.9199 Fax

SE Asia:
2 Corporation Road
#03-11/12
Corporation Place 618494
Singapore
+65 6749 0538 Phone
+65 6552 7116 Fax

Europe:
62 Basepoint
1 Winnall Valley Road
Winchester
Hampshire, SO23 0LD, UK
+44 (0) 1962 832654 Phone
+44 (0) 1962 832501 Fax

Japan:
TOC Ariake Building
West Tower 1F
3-5-7 Koto-ku Ariake
Tokyo, 135-0063, Japan
+81 3 5762 2801 Phone
+81 3 5762 2802 Fax

Copyright © 2015 Nordson YESTECH